

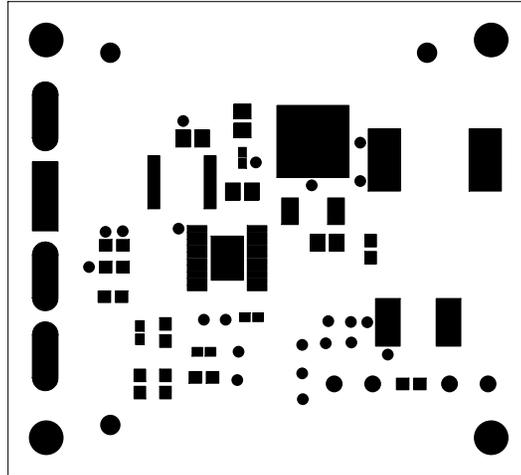
NATIONAL SEMICONDUCTOR		
DRILL DRAWING	BOARD NAME: LM25576 DEMO BOARD	BOARD NO:
DATE: 12/12/06		REV: A

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
■	24.02	+3.0/-3.0	PLATED	26
■	40.0	+3.0/-3.0	PLATED	4
○	66.14	+3.0/-3.0	PLATED	8
▲	125.0	+2.01/-2.01	NON-PLATED	4

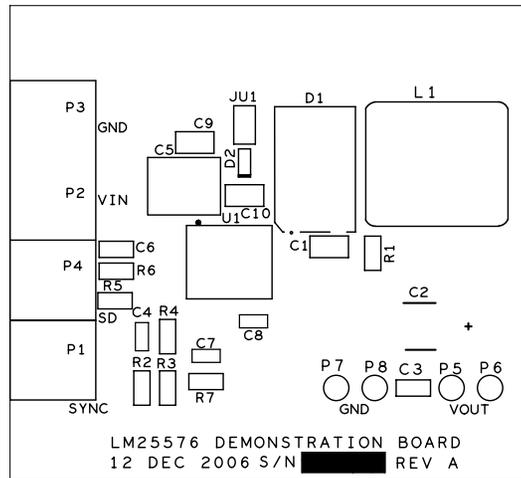
NOTES: (UNLESS OTHERWISE SPECIFIED)

- GENERAL
 - (A) THIS FABRICATION DRAWING APPLICABLE TO THE PRINTED CIRCUIT BOARD ARTWORK FILES SUPPLIED ALONG WITH THIS
 - (B) ANY MODIFICATIONS/DEVIATIONS TO THE ARTWORK FROM THESE NOTES MUST BE APPROVED BY HCL TECHNOLOGIES HOWEVER, MANUFACTURER CAN APPLY TEARDROPS, THIEVING, REMOVE NON FUNCTIONAL PADS AT THEIR DISCRETION TO IMPROVE MANUFACTURING YIELDS
 - (C) MARKING: SUPPLIER SHALL PERMANENTLY MARK PRINTED CIRCUIT BOARDS WITH THEIR DATE CODE
 - (D) MANUFACTURE TO COMPLY WITH IPC-6012A CLASS 3, TYPE 2, INSPECT AS PER IPC-A-610
 - (E) PACKAGE: FOR PROTECTION DURING SHIPPING AND HANDLING
- BOARD MATERIAL
 - (A) DIELECTRIC: EPOXY GLASS FR-4, HIGH TG>170 Deg C
 - (B) WARPAGE: BOW AND TWIST OF THE PCB SHALL NOT EXCEED 0.75% (PTH/SMT COMBINATION) IN ANY DIRECTION AS INSPECTED PER IPC-TM-650
- COPPER
 - (A) SEE DETAIL-A AND REFER BUILDUP.
- DRILLING
 - (A) FABRICATE USING THE PROVIDED EXCELLON DRILL FILE
 - (B) ALL HOLES EXCEPT TOOLING HOLE SHOULD BE DRILLED USING DATUM (0,0) +/- .005 INCHES
 - (C) DRILL HOLE TOLERANCES AS PER DRILL TABLE
- FINISHING
 - (A) SURFACE FINISH : HASL
 - (B) PLATING: ALL PLATED HOLES TO BE 0.001" THICK MIN
 - (C) SMOBC: USE LPI PER IPC-SM-840, COLOR-GREEN, ON BOTH SIDES
MANUFACTURER CAN MODIFY SOLDERMASK TO MEET MANUFACTURING, ASSEMBLING REQUIREMENTS
 - (D) SILKSCREEN: WHITE EPOXY, PERMANENT, NON-CONDUCTIVE, NON-NUTRIENT INK SHALL BE APPLIED ON BOTH SIDES
SHALL NOT COVER PADS, TEST POINTS AND HOLES.
ADD UL MARK UL94V-0, SUCH THAT THE MARK IS VISIBLE AFTER ASSEMBLING
 - (E) SOLDERABILITY OF PCB AS PER IPC-J-STD-003
- TEST
 - (A) VERIFY GERBER FILES AGAINST THE PROVIDED IPC-D-356A NETLIST FILE

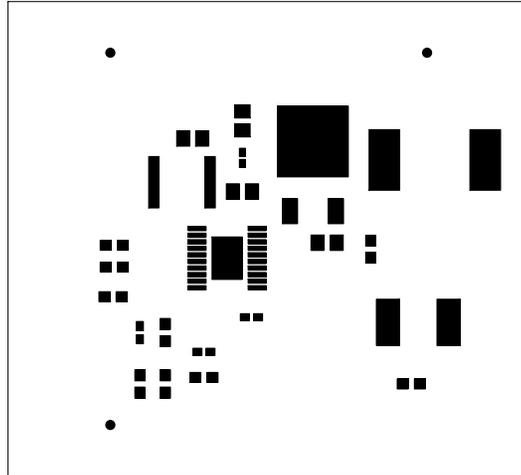
3									
2									
1									
REV.	DATE	DRAWN	APPR.	DRAWN		FSCM NO			SCALE
REPL. BY:				CHECKED		5 3960	NATIONAL SEMICONDUCTOR		
REPL. FOR:				APPR.					
							DWG NO		
LM25576 DEMONSTRATION BOARD							SHEET 1 OF 1		



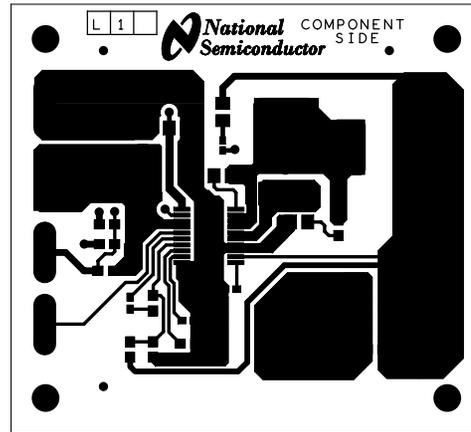
NATIONAL SEMICONDUCTOR		
SOLDERMASK TOP	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



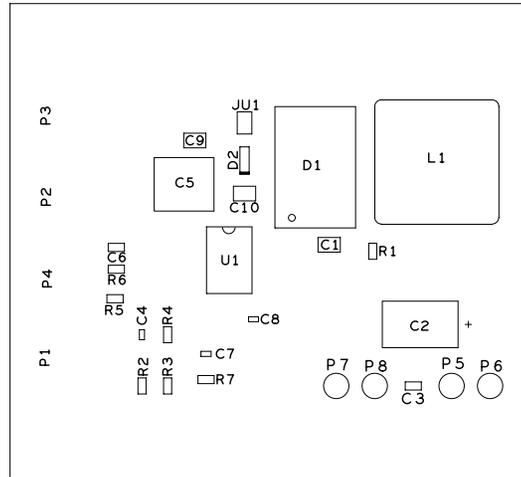
NATIONAL SEMICONDUCTOR		
SILKSCREEN TOP	BOARD NAME : LM2576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



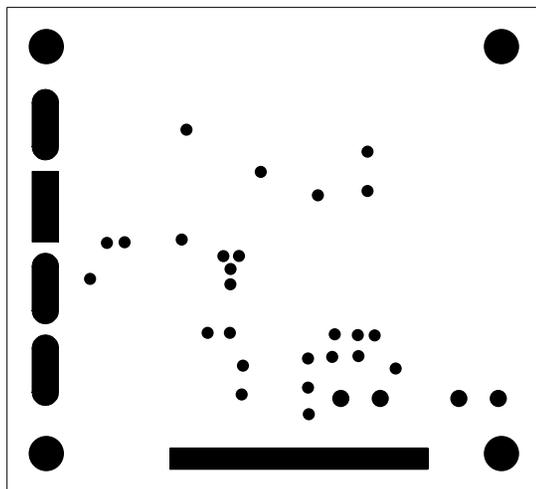
NATIONAL SEMICONDUCTOR		
PASTEMASK TOP	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



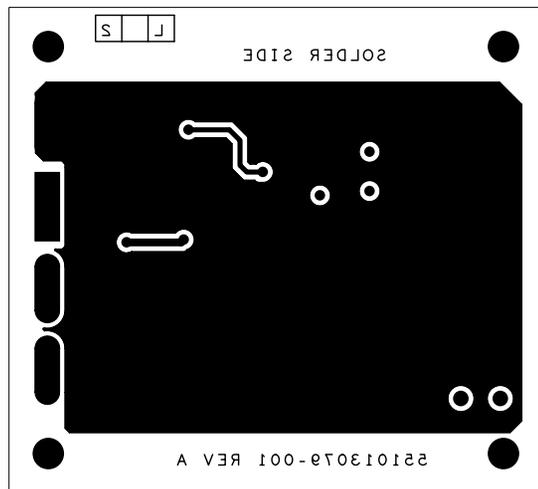
NATIONAL SEMICONDUCTOR		
TOP LAYER	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



NATIONAL SEMICONDUCTOR		
ASSEMBLY TOP	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



NATIONAL SEMICONDUCTOR		
SOLDERMASK BOTTOM	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A



NATIONAL SEMICONDUCTOR		
BOTTOM LAYER	BOARD NAME : LM25576 DEMO BOARD	BOARD NO :
DATE : 12/12/06		REV : A